

IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (currently amended): A package substrate ~~to which comprising:~~
~~an outermost interlayer resin insulating layer;~~
~~a pad structure formed on the outermost interlayer resin insulating layer;~~
~~a solder resist formed on the outermost interlayer resin insulating layer and the pad~~
~~structure, the solder resist having an opening exposing a partially exposed portion of the pad~~
~~structure;~~
~~a conductive connecting pin for establishing configured to establish [[the]] an~~
~~electrical connection with another substrate, the conductive connecting pin being [[is]]~~
~~secured[[,]] to the partially exposed portion of the pad structure via said package substrate~~
~~comprising: a pad formed on said substrate and arranged to secure said conductive~~
~~connecting pin, wherein said pad is coated with an organic resin insulating layer, said organic~~
~~resin insulating layer has an opening through which said pad is partially exposed to the~~
~~outside, and said conductive connecting pin is, through a conductive adhesive agent; and,~~
~~secured to said pad exposed through said opening~~
~~a via hole formed through the outermost interlayer resin insulating layer and~~
~~configured to electrically connect the pad structure to at least one conductive circuit formed~~
~~below the outermost interlayer resin insulating layer, the via hole being positioned directly~~
~~below the pad structure.~~

Claims 2-89 (canceled)

Claim 90 (new): The package structure according to claim 1, further comprising:
at least one conductor layer comprising a plurality of conductor circuits formed below
the outermost interlayer resin insulating layer; and

at least one interlayer resin insulating layer formed below the conductor layer, wherein the conductor layer and the interlayer resin insulating layer are alternately formed.

Claim 91 (new): The package structure according to claim 1, wherein the pad structure comprises an outermost conductor portion formed on the outermost interlayer resin insulating layer.

Claim 92 (new): The package structure according to claim 1, wherein the pad structure comprises an outermost conductor portion formed on the outermost interlayer resin insulating layer and the at least one conductor circuit is positioned directly below the pad structure.

Claim 93 (new): The package structure according to claim 90, wherein the pad structure comprises an outermost conductor portion formed on the outermost interlayer resin insulating layer and the at least one conductor circuit is positioned directly below the pad structure.

Claim 94 (new): The package structure according to claim 90, further comprises at least one lower via hole directly connected to the via hole and formed through the at least one interlayer resin insulating layer formed below the conductor layer, the at least one lower via hole being configured to electrically connect the via hole to at least one of the conductor circuits in the at least one conductor layer.

Claim 95 (new): The package structure according to claim 1, wherein the pad structure comprises a plane layer.

Claim 96 (new): The package structure according to claim 1, further comprising a signal line formed on the outermost interlayer resin insulating layer, wherein the signal line connects to the pad structure, and the signal line is covered with the solder resist.

Claim 97 (new): The package structure according to claim 1, wherein a diameter of the pad structure is 1.02 times to 100 times a diameter of the opening.

Claim 98 (new): The package structure according to claim 1, wherein the conductive connecting pin comprises a columnar connection portion and a plate-like secured portion, the secured portion is secured to the pad through the conductive adhesive agent, and the conductive connecting pin comprises at least one of Cu, a copper alloy, Ti, Zn, Al and a noble metal.

Claim 99 (new): The package structure according to claim 98, wherein the columnar connection portion has a constriction portion having a diameter which is smaller than a diameter of other portion.

Claim 100 (new): The package structure according to claim 1, wherein the pad structure has a roughened surface.

Claim 101 (new): The package structure according to claim 92, wherein the pad structure has a roughened surface.

Claim 102 (new): The package structure according to claim 94, wherein the pad structure has a roughened surface.

Claim 103 (new): A package substrate comprising:
an outermost interlayer resin insulating layer;
a pad structure formed on the outermost interlayer resin insulating layer;
a solder resist formed on the outermost interlayer resin insulating layer and the pad structure, the solder resist having an opening exposing a partially exposed portion of the pad structure;
conductive connecting means for establishing an electrical connection with another substrate, the conductive connecting means being secured to the partially exposed portion of the pad structure; and
a via hole formed through the outermost interlayer resin insulating layer and configured to electrically connect the pad structure to at least one conductive circuit formed

below the outermost interlayer resin insulating layer, the via hole being positioned directly below the pad structure.

Claim 104 (new): The package structure according to claim 103, further comprising:
at least one conductor layer comprising a plurality of conductor circuits formed below the outermost interlayer resin insulating layer; and
at least one interlayer resin insulating layer formed below the conductor layer,
wherein the conductor layer and the interlayer resin insulating layer are alternately formed.

Claim 105 (new): The package structure according to claim 103, wherein the pad structure comprises an outermost conductor portion formed on the outermost interlayer resin insulating layer.

Claim 106 (new): The package structure according to claim 103, wherein the pad structure comprises an outermost conductor portion formed on the outermost interlayer resin insulating layer and the at least one conductor circuit is positioned directly below the pad structure.

Claim 107 (new): The package structure according to claim 104, wherein the pad structure comprises an outermost conductor portion formed on the outermost interlayer resin insulating layer and the at least one conductor circuit is positioned directly below the pad structure.

Claim 108 (new): The package structure according to claim 104, further comprises at least one lower via hole directly connected to the via hole and formed through the at least one interlayer resin insulating layer formed below the conductor layer, the at least one lower via hole being configured to electrically connect the via hole to at least one of the conductor circuits in the at least one conductor layer.

Claim 109 (new): The package structure according to claim 103, wherein the pad structure comprises a plane layer.

Claim 110 (new): The package structure according to claim 103, further comprising a signal line formed on the outermost interlayer resin insulating layer, wherein the signal line connects to the pad structure, and the signal line is covered with the solder resist.

Claim 111 (new): The package structure according to claim 103, wherein a diameter of the pad structure is 1.02 times to 100 times a diameter of the opening.

Claim 112 (new): The package structure according to claim 103, wherein the conductive connecting means comprises at least one of Cu, a copper alloy, Ti, Zn, Al and a noble metal.

Claim 113 (new): The package structure according to claim 103, wherein the pad structure has a roughened surface.

Claim 114 (new): The package structure according to claim 106, wherein the pad structure has a roughened surface.

Claim 115 (new): The package structure according to claim 108, wherein the pad structure has a roughened surface.